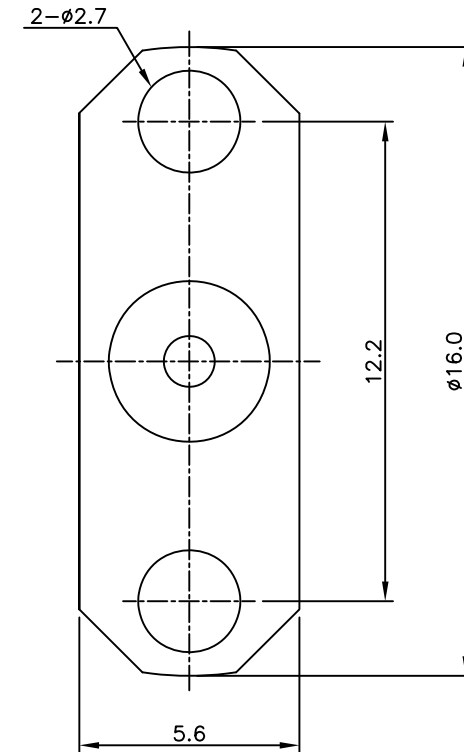
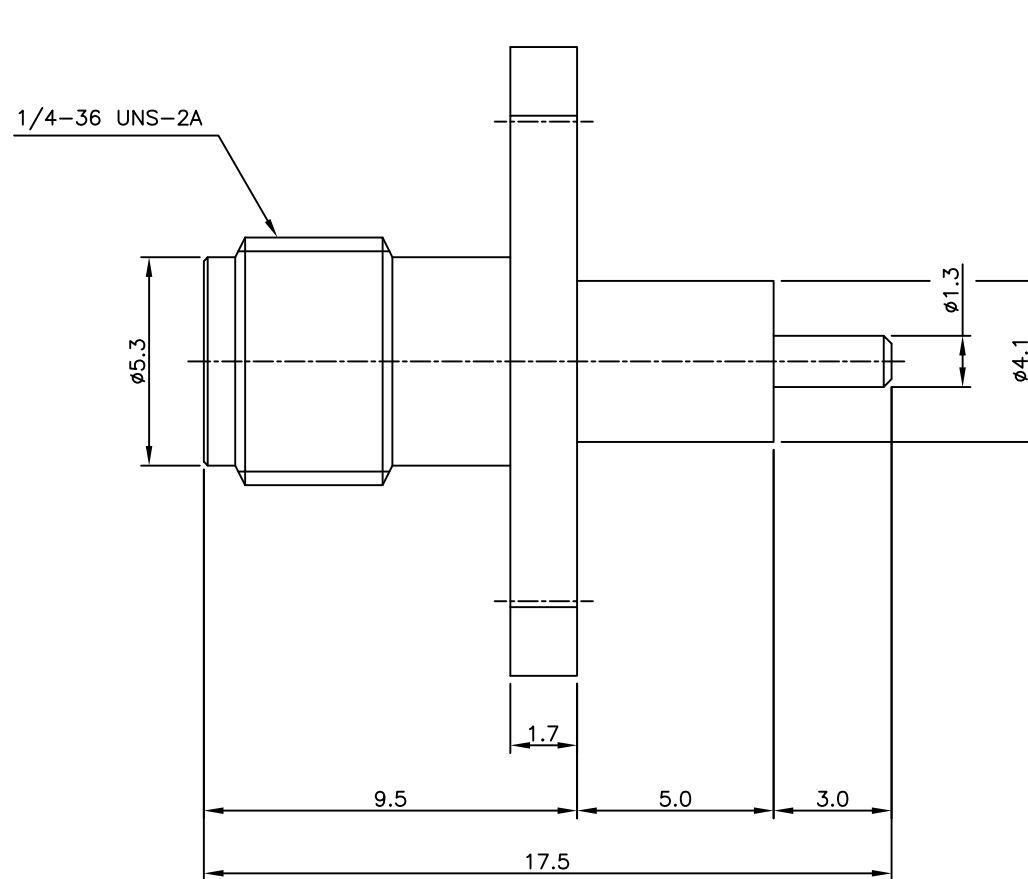
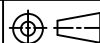


REVISION				
REV	DESCRIPTION	DRAWN	APPR	DATE
IR	Initial Registration			2007. 10. 16.
1	절연체 공용화로 인한 코드 변경	S.Y.EUN	I.C.KIM	2020. 12. 24.
2	PIN 공용화 제품 적용으로 인한 코드 변경	S.Y.EUN	S.H.KIM	2022. 08. 23.



1	3	INSULATOR	1	TEFLON		DIN02077-N/1 DIN00121-N/1 (H2132)
2	2	CONTACT	1	BeCu	Gold Plate	DCT01423-5/1 DCT00193-5/1 (E2022)
	1	BODY	1	MBsBD	Gold Plate	DBD00347-5/1 (D2036)
	NO.	DESCRIPTION	Q'TY	MATERIAL	PLATING	CODE

TOLERANCE	Decimal ±0.2	DATE 2022. 08. 23.		 RF & MICROWAVE TECHNOLOGY Tel : 82-32-347-8015 Fax : 82-32-347-8017		
	Angle ±1°	APPROVED BY S.H.KIM				
MATERIAL -		CHECKED BY		TITLE SMA50 SOLDER END J-H2		
		DRAWN BY S.Y.EUN				
FINISH -	SCALE 5/1	UNIT mm		A4	DWG NO. CN01108-7/1	
					REVISION 2	SHEET 1 of 1